

**COMPOSITE LAMINATE CIRCUIT STRUCTURE AND
METHODS OF FABRICATING**

ABSTRACT OF DISCLOSURE

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A laminate circuit structure assembly is provided that comprises at least two modularized circuitized voltage plane subassemblies; optionally an interposer located between each of the subassemblies and wherein the subassemblies and interposer, if present, are bonded together with a cured dielectric coating. The interposer comprises dielectric layers disposed about an internal electrically conductive layer.